

In the Claims:

1. (previously presented) An apparatus for cleaning a polishing pad of a chemical-mechanical polishing system which includes a first drive device coupled with said polishing pad for turning said polishing pad on a center axis in a first direction and a second drive device for moving said wafer into mechanical contact with said polishing pad and for rotating said wafer in a direction opposite to said first direction, comprising:

a dispenser located in proximity above said polishing pad for dispensing a slurry to said polishing pad, said slurry cooperable with said mechanical contact for effecting polishing of said wafer, said dispenser further including a plurality of nozzles each nozzle for delivering a wash solution to said polishing pad for cleaning said slurry from said polishing pad; and

an extension on said dispenser coupled to a distal end of said dispenser for delivering said wash solution to an area proximate to and including said center axis for cleaning said slurry from said polishing pad.

2. (previously presented) The apparatus of Claim 1, wherein said extension includes piping and a spray nozzle, said piping coupled to and extending from said dispenser toward said center axis, said spray nozzle coupled to said piping and cooperable therewith to direct a water spray to said polishing pad at a ninety degree angle.

3. (previously presented) The apparatus of Claim 1, wherein said extension further includes a adjustor coupled to said piping for extending the distance of the spray nozzle from said extension distal end.

4. (previously presented) The apparatus of Claim 2, wherein said spray nozzle is held in a position by said piping proximate said center axis directly above said polishing pad.

5. (previously presented) The apparatus of Claim 1, wherein said dispenser dispensing said wash material to said polishing pad all along an area from the circumference of said polishing surface to said center axis.

6. (previously presented) The apparatus of Claim 1, wherein said extension delivers said wash solution to an area proximate to said center axis without any portion of said extension extending past the distal end of said dispenser toward said center axis.

7. (previously presented) A system for chemical mechanical polishing of semiconductor wafers, said system comprising:

a first drive device coupled with a polishing pad of a circular shape for turning said polishing pad on a center axis in a first direction;

a dispenser located in proximity above said polishing pad for dispensing a slurry to said polishing pad;

a second drive device for moving said wafer into mechanical contact with said polishing pad and rotating said wafer in a direction opposite to said first direction and cooperable with said dispensed slurry for effecting polishing of said wafer;

said dispenser further including a plurality of nozzles, each nozzle for delivering a wash solution to said polishing pad; and

an extension on said dispenser coupling to a distal end of said dispenser for delivering said wash solution to an area proximate to and including said center axis for cleaning said slurry from said polishing pad.

8. (previously presented) The system of Claim 7, wherein said extension includes piping and a spray nozzle, said piping coupled to and extending from said dispenser toward said center axis, said spray nozzle coupled to said piping and cooperable therewith to direct a water spray to said polishing pad at a ninety degree angle.

9. (previously presented) The system of Claim 7, wherein said extension further includes an adjustor coupled to said piping for extending the distance of the spray nozzle from said extension distal end.

10. (previously presented) The system of Claim 8, wherein said spray nozzle is held in a position by said piping proximate said center axis directly above said polishing pad.

11. (previously presented) The system of Claim 7, wherein said delivers said wash solution to an area proximate to said center axis without any portion of said extension extending past the distal end of said dispenser toward said center axis.

12. (previously presented) A method for cleaning a polishing pad in a chemical mechanical polishing system, comprising the steps:

imparting relative motion to said polishing pad, wherein said polishing pad is rotated about a center axis which is perpendicular to the polishing surface of said polishing pad; and

dispensing a wash material directly to the most center portion of said polishing surface about and including said axis.

13. (currently amended) The method of Claim 12, further including providing a spray arm for dispensing said wash material and providing a spray extension which is coupled to a ~~the~~ dispensing arm of said chemical mechanical polishing system for dispensing said wash material directly to the most center portion of said polishing surface about and including said axis.

14. (previously presented) The method of Claim 12, further comprising dispensing a de-ionized water solution directly to the most center portion of the polishing surface about said axis following polishing of a semiconductor wafer.

15. (previously presented) The method of Claim 12, further comprising dispensing wash material from said dispensing arm to said polishing pad all along an area from the circumference of said polishing surface to said axis.